Advanced Reflow Soldering Seminar

Temperature Profiling and Troubleshooting

June 9, 2026 in Timisoara, Romania

Today reflow soldering is still the most important connection technology for electronic assemblies. Our Advanced Reflow Soldering Seminar in Timisoara will focus on several important factors that influence the reflow soldering quality: What are the main aspects of an optimal soldering profile? How can you avoid common and special defect mechanisms? You can discuss your problems concerning reflow soldering with experts in this field. Rehm Thermal Systems invites you to broaden your horizon at this opportunity and welcomes you to Timisoara.

09:30 a.m. **Welcome and Introduction**
Andreas Heltmann, Rehm Thermal Systems

09:45 a.m. **PCB-Design**
> Design-to-Cost and Design for Manufacturing (DFM)
Lukas Filser, ATS

10:45 a.m. **Temperature Profiling, Vacuum Reflow, and Void Reduction – Latest IEC Technical Reports**
> Measurement methods, tolerances, and acceptance criteria
Dr. Paul Wild, Rehm Thermal Systems

11:15 a.m. **Coffee Break**

11:30 a.m. **Solder Paste Chemistry and its Behaviour during Reflow Soldering**
> Future Trends in Solder Pastes & Low-Temperature Soldering (LTS), Formic Acid
Cristian Tudor, Indium

12:30 p.m. **Lunch break**

1:15 p.m. **Soldering With and Without Nitrogen**
> Advantages and disadvantages
Dr. Paul Wild, Rehm Thermal Systems

1:45 p.m. **New Trends in Soldering – Systems and Process Technology**
> Low-Temperature Soldering (LTS),
> Formic Acid
Dr. Paul Wild, Rehm Thermal Systems

2:15 p.m. **Coffee Break**

2:45 p.m. **Troubleshooting**
> Whiskers and Black-Pad
> Wicking and Graping
> Voids
Dr. Paul Wild, Rehm Thermal Systems

3:45 p.m. **Perfect maintenance – Perfect Soldering**
> Filters, heat exchangers cleaning,
> Oven interior manual cleaning
Jaroslav Jalový, DCT

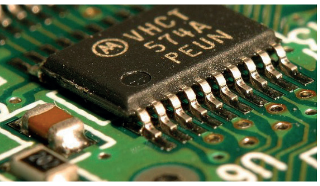
4:45 p.m. **End of seminar**
Time for discussions and Get-Together

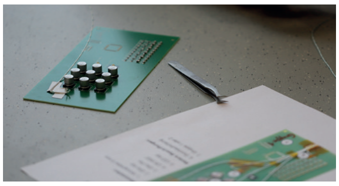
Attendance fees *including beverage, lunch and seminar material*

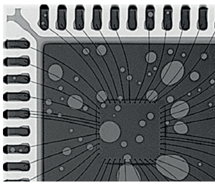
129,00 € per day >> registration **before** May 22, 2026
149,00 € per day >> registration **after** may 22, 2026

Register for both days and get an extra discount of 10% on the above attendance fee!

Subject to substantive adjustments



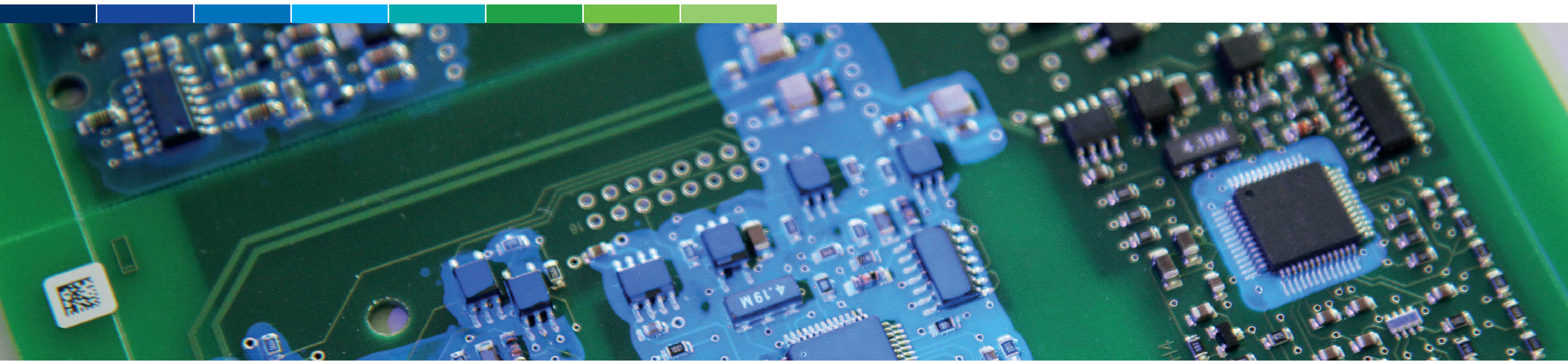




TECHNOLOGY ACADEMY
Advanced Reflow Soldering Seminar

Advanced Conformal Coating Seminar

Conformal Coating



June 10, 2026 in Timisoara, Romania

How do you ensure sustainable PCB protection for your electronic components? The coating technology in the electronics industry continues to advance. The wide range of materials and application methods are specially adapted to the assembly to be produced. It is not easy not to lose the overview here. On the second day of our seminar, you will learn about the basics and the diversity of coating technology and smart communication in line through to failure analysis of your coated product.

09:30 a.m.	**Welcome and Introduction** *Andreas Heltmann, Rehm Thermal Systems* *Gianfranco Sinistra, Rehm Thermal Systems*
09:45 a.m.	**Where Conformal Coating Meets the PCB** > Material Interfaces and Surface Quality for a Reliable Protection *Jonatan Milione, NCAB*
10:45 a.m.	**Different materials** > Conformal Coating Materials in Electronics: Chemistry groups and Selection Frameworks *Balint Gyorffy, HumiSeal*
11:15 a.m.	**Coffee Break**
11:45 a.m.	**Variety of Coating Technologies** > Which material for which application? And How To do a easy program? *Gianfranco Sinistra, Rehm Thermal Systems*
12:45 p.m.	**Lunch Break**
1:15 p.m.	**Cleaning: Pro and Cons** > Challenges, what if not *Jaroslav Jalový, DCT*
2:00 p.m.	**Failure Analysis** > During the production process, On the product *Gianfranco Sinistra, Rehm Thermal Systems*
2:45 p.m.	**Coffee Break**
3:15 p.m.	**Workpiece Carrier** > Process hallenges, material and cleaning > Project management *Oliver Hagemes, Rösnick*
4:00 p.m.	**Line Connectivity** >Smart Communications *Gianfranco Sinistra, Rehm Thermal Systems*
3.30 p.m.	**End of Seminar** Time for Discussions and Get-Together

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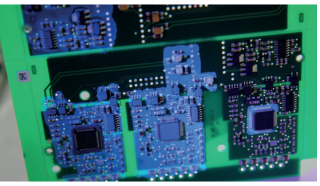

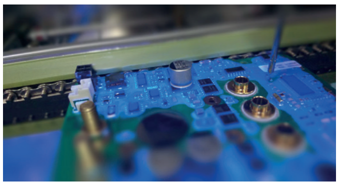

TECHNOLOGY ACADEMY
Advanced Reflow Soldering Seminar

THERMAL SYSTEMS

Registration to the Advanced Reflow Soldering and Conformal Coating Seminar in Timisoara

EARLY BOOKING DISCOUNT

Your participation ☐ **June 9, 2026** ☐ **June 10, 2026**

129,00 € per day >> registration **before** May 22, 2026

149,00 € per day >> registration **after** May 22, 2026

Register for both days and get an extra discount of 10% on the participation fee!

Subject to a minimum number of 20 participants

I will participate in the seminar with ______ person(s) in total.

Company:

Participant(s):

Address:

Post Code: City:

Country: Phone:

E-Mail:

Different billing address:

Contact person for invoice:
(Name and E-Mail)

VAT identification number:

- » Return by E-Mail: sales@rehm-group.com
- » Or register on our Website: www.rehm-group.com/en/news/dates

Location of the seminar is **HOTEL TIMISOARA, 300086 Marasesti Str. 1-3, Timisoara, Romania**.
If you need an accommodation you can book a room from our contingent with the keyword.

Keyord: **REHM2026 (only by e-mail)**

Mrs. Simona Andreica | E-Mail: office@hoteltimisoara.ro
Phone: +40 256 498 852 | Web: www.hoteltimisoara.ro

The price for one single room is 90 € (Business room) per night incl. breakfast.